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IN THE U.S. PATENT AND TRADEMARK OFFICE

APPLICANTS: Kenneth A. Peterson & Robert D. Watson  
SERIAL NO.: Unknown GROUP NO.  
FILED: EXAMINER:  
FOR: Bi-Level Microelectronic Device Package with an Integral Window  
Assistant Commissioner for Patents  
Washington, D.C. 20231

J1002 U.S. PRO  
10/082961  
02/25/02

February 25, 2002

INFORMATION DISCLOSURE STATEMENT

The following sections are being submitted for this Information Disclosure Statement:

1. Preliminary Statements

Applicants submit herewith patents, publications or other information of which they are aware, which they believe may be material to the examination of this application and in respect of which there may be a duty to disclose.

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2. Form PTO - 1449 (Modified).

3. The person making this statement is the attorney or agent who signs below on the basis of the information supplied by the inventor(s) and the information in the attorney's or agent's file.

Dated: 2/25/02

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CERTIFICATE OF MAILING

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the U. S. Postal Service on the date shown below as Express Mail No. EL026587084US in an envelope addressed to the: Assistant Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.

Dated: 2/25/02

Viola Campos  
Viola Campos

Form PTO-1449 (SNL-Modified) (2-91)  
List of Patents and Publications  
for Applicant's  
Information Disclosure Statement

(use several sheets if necessary)

Atty Docket No: SD-7122/S-98,720  
Serial Number:

APPLICANT: Kenneth A. Peterson, et al

GROUP: FILING DATE: 2/25/02

### REFERENCE DESIGNATION

Ex'r Init				U.S. Patent Documents		Sub		
		Document No.	Date	Name		Class	Class	File Date
	AA	6,335,224	6/1/02	Protection of Microelectronic, ...		438	114	5/16/00
	AB	5,600,541	2/4/97	Vertical IC Chip Stack...		361	707	8/3/95
	AC	5,729,038	3/17/98	Silicon-Glass Bonded Wafers		257	460	12/15/95
	AD	5,357,056	10/18/94	Chip Carrier For Optical Device		174	524	3/23/93
	AE	5,864,381	1/26/99	Automated Pupil Remapping...		351	205	7/10/96
	AF	5,493,391	2/20/96	One Dimensional Wavefront...		356	121	7/11/94
	AG	5,352,852	10/4/94	Charge Coupled Device Package...		174	52.4	8/3/93
	AH	4,742,182	5/3/88	Flatpack for Hermetic...		174	52	11/6/86

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10/082961  
02/25/02

			Foreign Patent Documents		Sub	Translation	
	Document No.	Date	Name	Class	Class	Yes	No

### OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

- |BA |Kenneth A. Peterson, et al; "Pre-Release Plastic Packaging of MEMS and IMEMS Devices"  
Patent Application 09/572,720 filed 5/16/00.
- |BB |Kenneth A. Peterson, et al, "Microelectronic Device Package with an Integral Window";  
Serial No. 09/571,335; filed 5/16/00; Notice of Allowance 2/6/01.
- |BC |M.L. Minges, et al., "Electronic Materials Handbook, Vol. 1, PACKAGING", ASM International, Materials  
Park, OH, Jan., 1989, pp. 461-469.

Examiner:

Date Considered: